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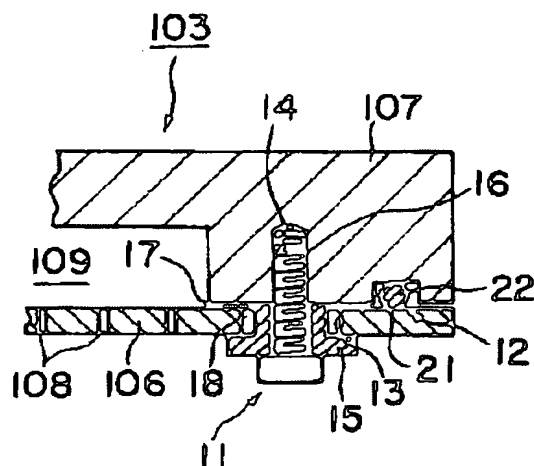
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TITLE : HIGH-FREQUENCY ELECTRODE
DEVICE OF SUBSTRATE TREATMENT
DEVICE



11 : 固定部	21 : 溝
12 : 電気的接点部	22 : 接電部材
13 : 孔	103 : 電極装置
14 : ネジ孔	106 : 導体板
15 : スペース	107 : 支持構造体
16 : ネジ	

ABSTRACT : PROBLEM TO BE SOLVED: To provide a high-frequency electrode device which improves electrical connection between a conductor plate and its supporter structure and prevents the conductor plate from occurrence of its bended condition due to thermal expansion, in a substrate treatment device using high-frequency discharge.

SOLUTION: This high-frequency electrode device 103 comprises a conductor plate 106 and a supporter structure 107 which fixes the former with a screw 16, high frequency (of 60 MHz or more, desirably) is supplied to the conductor plate through the supporter structure and its contact part, and discharge is made by using this high frequency. Further, the high-frequency electrode device is provided with a gap 18 and a loose contact condition 17 that enable the elongation of the conductor plate with a conductor-plate fixation part 11, and an electricity-supply contact part 12 which supplies high frequency wave to the conductor plate is arranged between the conductor plate and the supporter structure, other than the conductor-plate fixation part. In the electricity-supply contact part 12, an electrical-connection member 22 with a springiness is used.

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